PCB Layer Stack-up

Through via Via123456

Top silk screen
Top solder resist
Top Au plate thickness= 17.5um

6.8mil (173um) 2113 Fr4 Prepreg 3/8oz (12um Foil)

8mil (200um) Fr4 Core 1/2oz 1/2oz Cu (18um/18um)

30mil (750um) Fr4 Core/Prepreg Packing

8mil (200um) Fr4 Core 1/2oz 1/2oz Cu (18um/18um)

6.8mil (173um) 2113 Fr4 Prepreg 3/8oz (12um Foil)

Bottom Au plate thickness=17.5um
Bottom solder resist
Top silk screen

MYRIAD RF